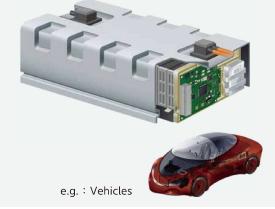
Non-Conductive Via Filling Paste

Over 20-year experience for automotive and high-end industries

Applications

Industrial/automotive industries (High Tg requirement)



Home electronics (High deinsity wiring)



e.g. : Gaming devices



Features

- Excellent adhesion to various material surfaces including copper foil
- Solvent-free enabling void/crack-free
- Contribution to high-density routing and/or multi-layer build-up



Product line-up & properties

| Product | | | AE1125HD | AE1125DS |
|-------------------------------------------|-------------|-------|-------------------|-------------|
| Viscosity | BH type | dPa∙s | 1,200 - 2,000 | 800 - 1,600 |
| Curing conditions | Pre-curing | | 80°C × 30min. | |
| | Post-curing | | 160°C×60min. | |
| Volume resistivity (Representative value) | | Ω·cm | 1.0E+09 - 1.0E+12 | |
| Thermal conductivity (Laser flash method) | | W/m∙k | 1.4 | 1.1 |
| Glass-transition temperature/Tg | | °C | 163 | 210 |